

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TATSUMI et al.

Serial No.: New Application

Group Art Unit:

AJAN DAN 16 Jan 187

Filed: August 10, 2001

Examiner:

For:

ELECTROSTATIC CHUCKING DEVICE AND MANUFACTURING

METHOD THEREOF

PRELIMINARY AMENDMENT

Commissioner for Patents Washington, D.C. 20231

August 10, 2001

Sir:

Prior to calculation of the filing fee and prior to the examination of this application, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims as follows. A copy of the marked-up original claims is attached showing the changes as set forth in amended 37 C.F.R. 1.121.

4. (Amended) An electrostatic chucking device according to claim 1 or 2, wherein the polyimide films which constitute the first insulation layer and the second insulation layer have a film thickness of 20 to 50 μm.